



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-03
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement	
Supplier Acceptance *	true
Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	BCG(*V788AEJ	A	CA2A	2016-06-03
Amount	UoM	Unit type	ST ECOPACK Grade	
20.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	2x3x0.6	10	No lead	
Comment	Package: A0Y4 UDFPN 2X3X0.6 10L PITCH 0.5; MDF valid for STC3115AIQT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	BCG(*V788AEJ)					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.065	mg	supplier	die	Silicon (Si)	7440-21-3		0.998	mg	937089	49900
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	5634	300
				supplier	metallization	Copper (Cu)	7440-50-8		0.023	mg	21596	1150
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.006	mg	5634	300
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1878	100
				supplier	Passivation	Silicon Nitride	12033-89-5		0.007	mg	6573	350
Leadframe	Copper & its alloys	8.221	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.023	mg	21596	1150
				supplier	alloy	Copper (Cu)	7440-50-8		7.935	mg	965211	396750
				supplier	alloy	Iron (Fe)	7439-89-6		0.187	mg	22747	9350
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.011	mg	1338	550
				supplier	alloy	Zinc (Zn)	7440-66-6		0.010	mg	1216	500
				supplier	metallization	Nickel (Ni)	7440-02-0		0.071	mg	8636	3550
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	608	250
				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	243	100
				supplier	Other Organic Materials	Fused Silica	60676-86-0		0.127	mg	686486	6350
				supplier	tape	Benzaldehyde, 2-hydroxy- polymer	120206-26-0		0.033	mg	178378	1650
Die attach	Other Organic Materials	0.185	mg	supplier	tape	Epoxyde Bisphenol A Resin	25068-38-6		0.020	mg	108108	1000
				supplier	tape	Dicyandiamide	461-58-5		0.005	mg	27027	250
				supplier	wire	Gold (Au)	7440-57-5		0.116	mg	991453	5800
				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	8547	50
Encapsulation	Other Organic Materials	10.412	mg	supplier	mold compound	Silica, vitreous	60676-86-0		9.423	mg	905013	471150
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.260	mg	24971	13000
				supplier	mold compound	Epoxy Resin	Proprietary		0.417	mg	40050	20850
				supplier	mold compound	Phenol Resin	Proprietary		0.260	mg	24971	13000
				supplier	mold compound	Carbon black	1333-86-4		0.052	mg	4994	2600